As an inventor named below or on a[illegible]ched continuation page, I hereby declare tha
My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled HERMETIC CHIP SIZE PACKAGE AND METHOD OF MANUFACTURE, the specification of which (check one):

- ■ is attached hereto.
- □ was filed on _____ as United States application serial no. _____ and was amended on _____.
- □ was filed on _____ as PCT international application no. _____ and was amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

(number)	(country)	(day/month/year filed)	Priority Claimed Yes	No
(number)	(country)	(day/month/year filed)	Yes	No

□ I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application(s) and the national or PCT international filing date of this application:

(application serial no.)	(filing date)	(status - pending, patented or abandoned)
(application serial no.)	(filing date)	(status - pending, patented or abandoned)

□ I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

(provisional application no.)	(filing date)
(provisional application no.)	(filing date)
(provisional application no.)	(filing date)

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012	William S. Britt, Reg. No. 20,969	Thomas J. Rossa, Reg. No. 26,799
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: Warren M. Farnworth
Inventor's signature X Warren M. Farnworth Date X 3-6-96
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DECLARATION FOR PATENT APPLICATION
(continuation page)

Invention title: HERMETIC CHIP SIZE PACKAGE AND METHOD OF MANUFACTURE

Inventor name(s) appearing on first declaration page: Warren M. Farnworth

☒ Additional original, first and joint inventor(s):

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